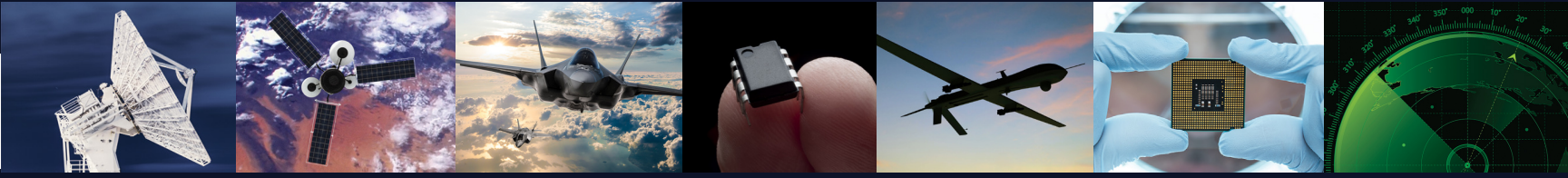


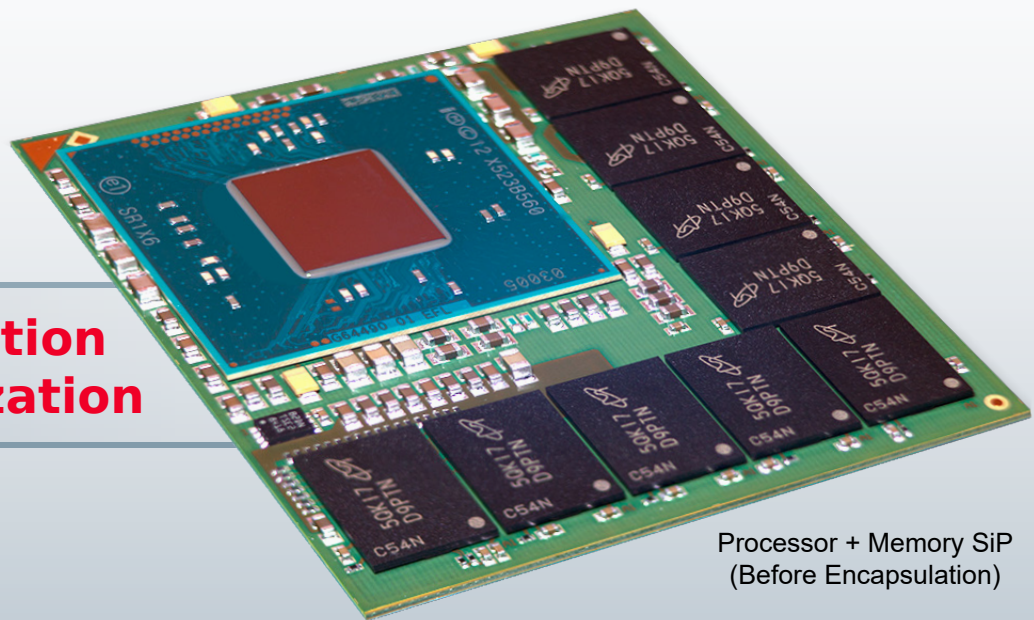
**MINIATURIZATION | RUGGEDIZATION | CUSTOMIZATION**



# SMALLER, TOUGHER, CUSTOM MICROELECTRONIC MODULES

One supplier to design, manufacture and test high-reliability, SWaP-C optimized solutions for mission critical applications.

**Miniaturization  
& Ruggedization**



Processor + Memory SiP  
(Before Encapsulation)

Assembled  
in the USA



Vertically integrated manufacturing enables ISI to quickly deliver miniaturized and ruggedized prototype and production modules

ISI is your one-stop supplier for highly engineered, ruggedized, custom microelectronic modules. We are fast to market with our in house prototyping and production manufacturing of complex electronic assemblies.

Our highly experienced design teams can deliver high-quality solutions for your most demanding electronics packaging challenges. ISI's design expertise is complemented by decades of experience in manufacturing process and test development, which ensures we produce high-reliability, miniaturized and ruggedized microelectronic modules, tailored to meet your specific requirements.

## DESIGN

- System Level Engineering
- 3D Advanced Packaging
- PCB & Substrate Design
- Harsh Environment

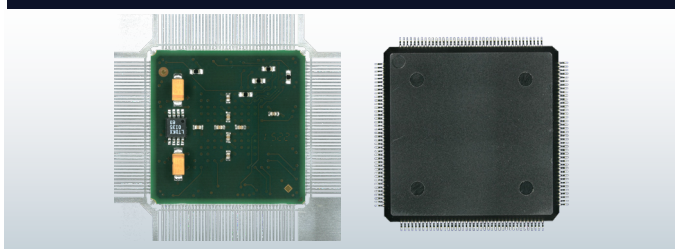


## MANUFACTURING

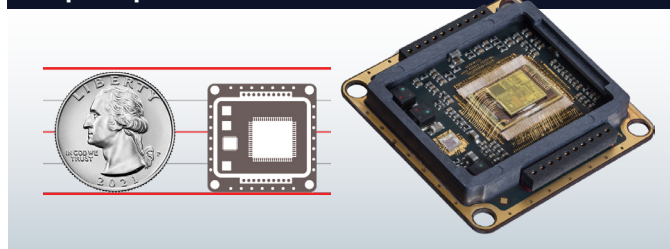
- Microelectronics Assembly
- Electronics Overmolding
- Interconnect
- Test & Inspection

# One company with many capabilities

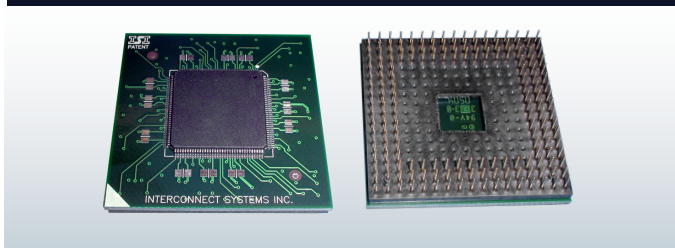
## Leadframe



## Flip Chip/Wire Bond Module



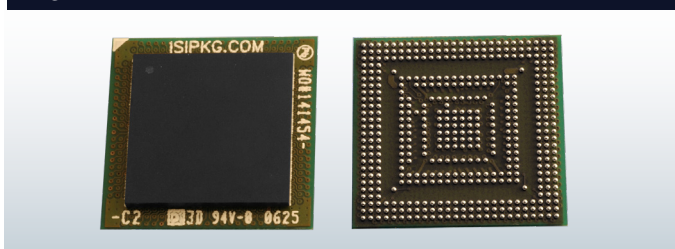
## PGA



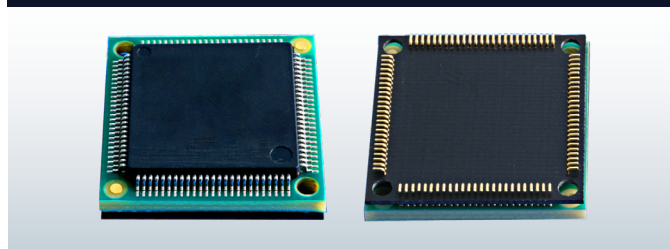
## Custom Complex Assembly



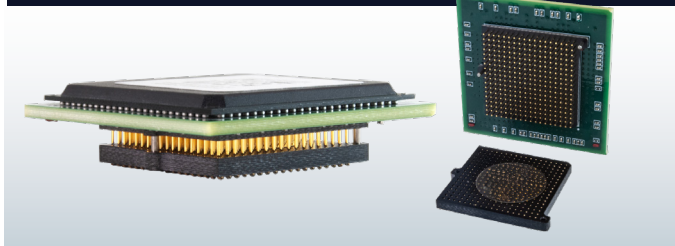
## BGA



## Flexframe



## Socketed Module



## Ruggedized & Miniaturized SiP

